

炭素のケミカルスパッタリングIII(O, N衝撃効果)

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Background

: Graphite for fusion-plasma walls

Summary of H(D) on pure-graphite [2007 Report]

- Chemical sputtering: Reaction of H(D) with C, formation and escape of hydrocarbons.
 - * For H energy > 0.3 keV, yield takes maximum at Ts~800K, CH₄ dominant, larger by an order of magnitude than physical sputtering
 - e.g. ~0.01 /ion for 1 keV H , Matsunami et al. ADNDT 31(1984)1., Yamamura et al. ADNDT62(1996)149.
 - For low energy, Ts~600K, contribution other than CH₄ becomes larger.
- * c.f. Enhanced sublimation, >1200K, Philips et al. JNM 155-157(1988)319.
- *NB. Reflection, ~0.1 at 1 keV H on C, Tabata et al. NIM B9(1985)113
- *Related phenomena: Reemission, Retention

Summary of H(D) on doped-graphite [2008 Report]

Dopant (10 elements)

B, Be

Si, Ti, W, V, Fe, Cr, Li, Zr

Suppression of chemical sputtering,

~10 % doping is effective.

Literatures

Review

1. J. Roth, "Chemical Sputtering", in Sputtering by Particle Bombardment II, ed. R. Behrisch, Springer-Verlag, 1983.
2. C. Garcia-Rosales, "Erosion processes in plasma-wall Interactions", J. Nucl. Mat. 211(1994)202.
3. J. W. Davis, A. A. Haasz, "Impurity release from low-Z materials under light particle bombardment", J. Nucl. Mat. 241-243(1997)37.

*Chemical sputtering: ~30 papers, 1976~2000: graphite [2007 Report]
*Doped-graphite : ~10 papers [2008 Report]
* O, N impact on graphite: ~20 papers [2009 Report]

Aim

- * **Data compilation & understanding of chemical sputtering of graphite: O, N impact**
- * **Control of chemical sputtering**

Temperature Dependence

2.5 keV O on graphite

*Temp. dependence ~ weak

c.f. H impact: strong temp. dep.

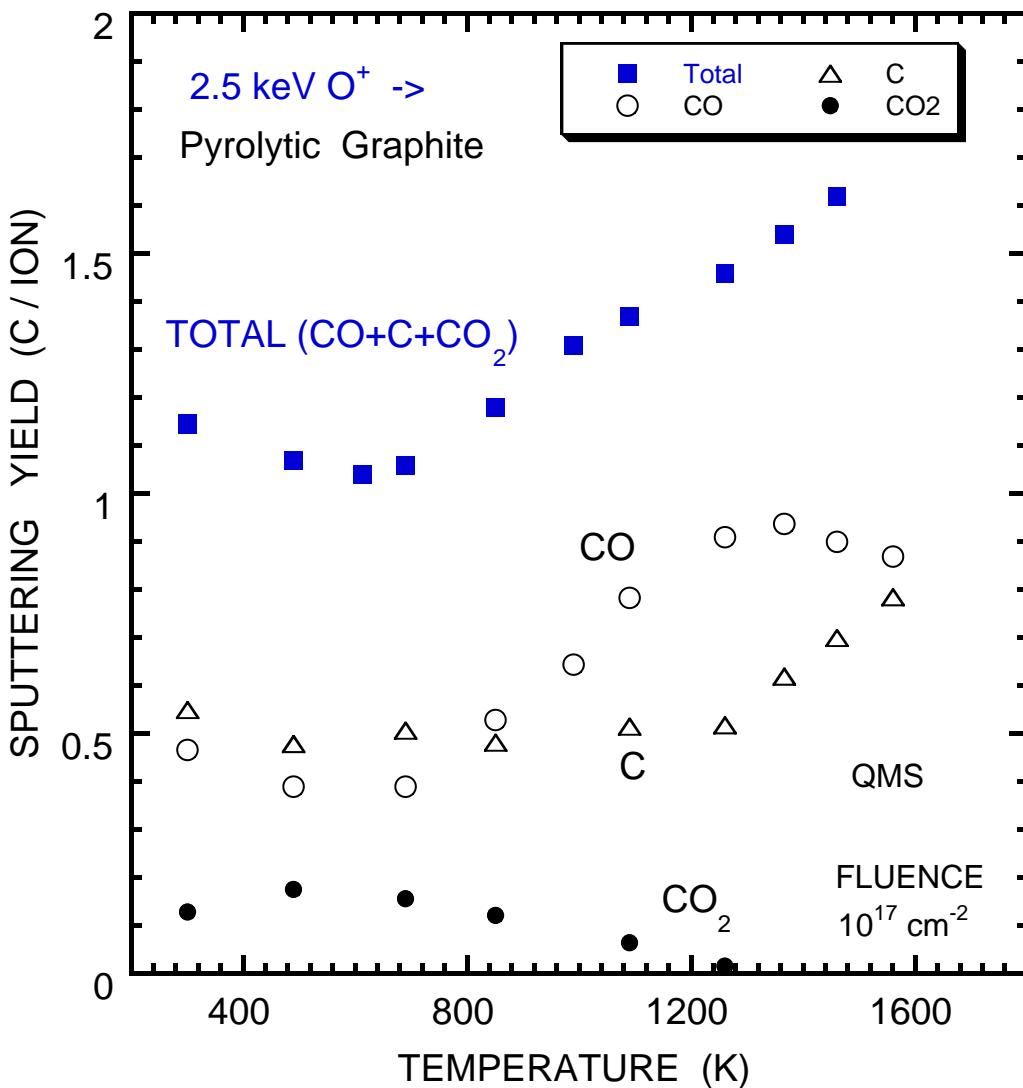
* Enhanced sublimation >1200 K

* CO & CO₂
CO is dominant .

Phys. Sputtering ~0.5

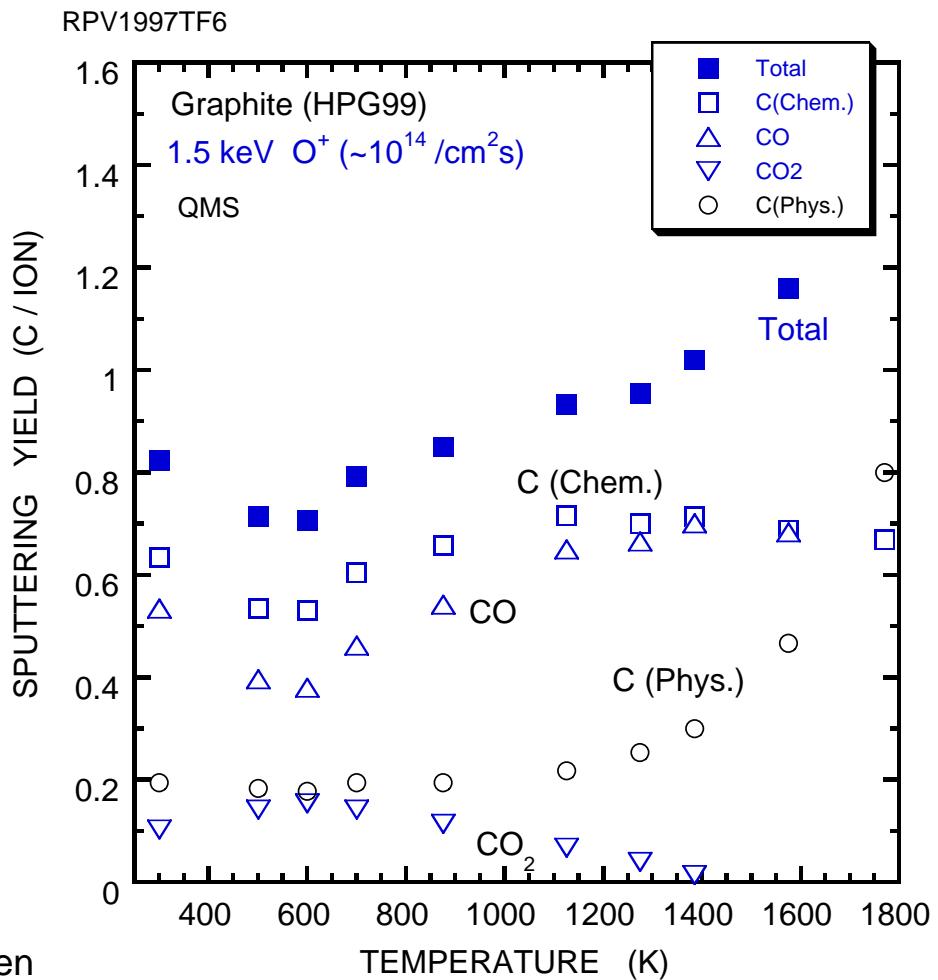
c.f. Calc. =0.8 (1984)

VTP1987TF2



Temperature Dependence

- *Temp. dependence ~ weak
- *Chem. Sp. > Phys. Sp.



Normal incidence. QMS-LOS and TOF have been used and the energy distribution has been considered. C (Chem.) : chemical sputtering yield, C (Phys.): physical sputtering yield and enhanced sublimation starts at ~1300 K.

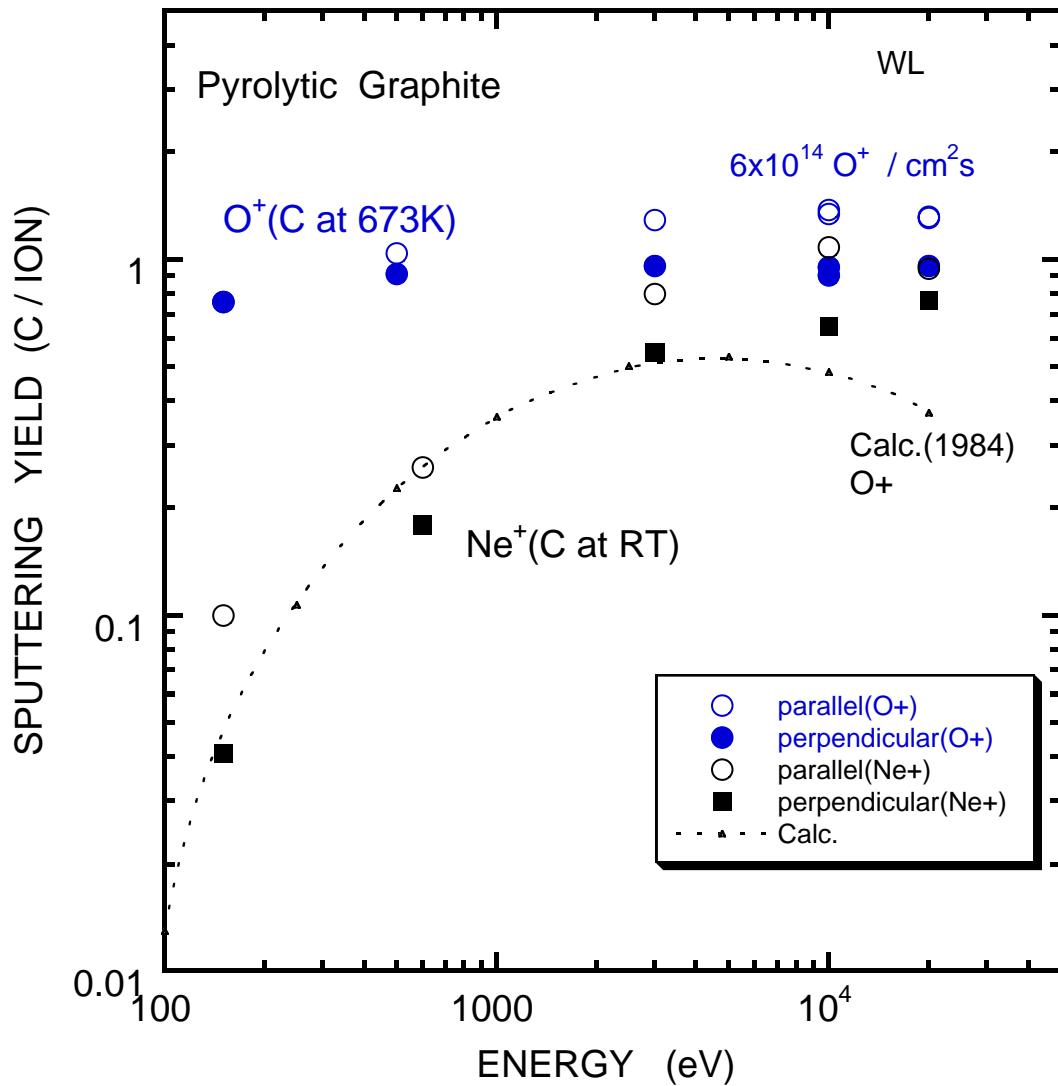
A. Refke, V. Philipps, E. Vietzke, J. Nucl. Mater. 250(1997)13.

Energy Dependence

*Weak

*Chem. Sp. \geq Phys. Sp.

HB1986EF2z



E. Hecht, J. Bohdansky,
J. Nucl. Mater. 141-143(1986)139.

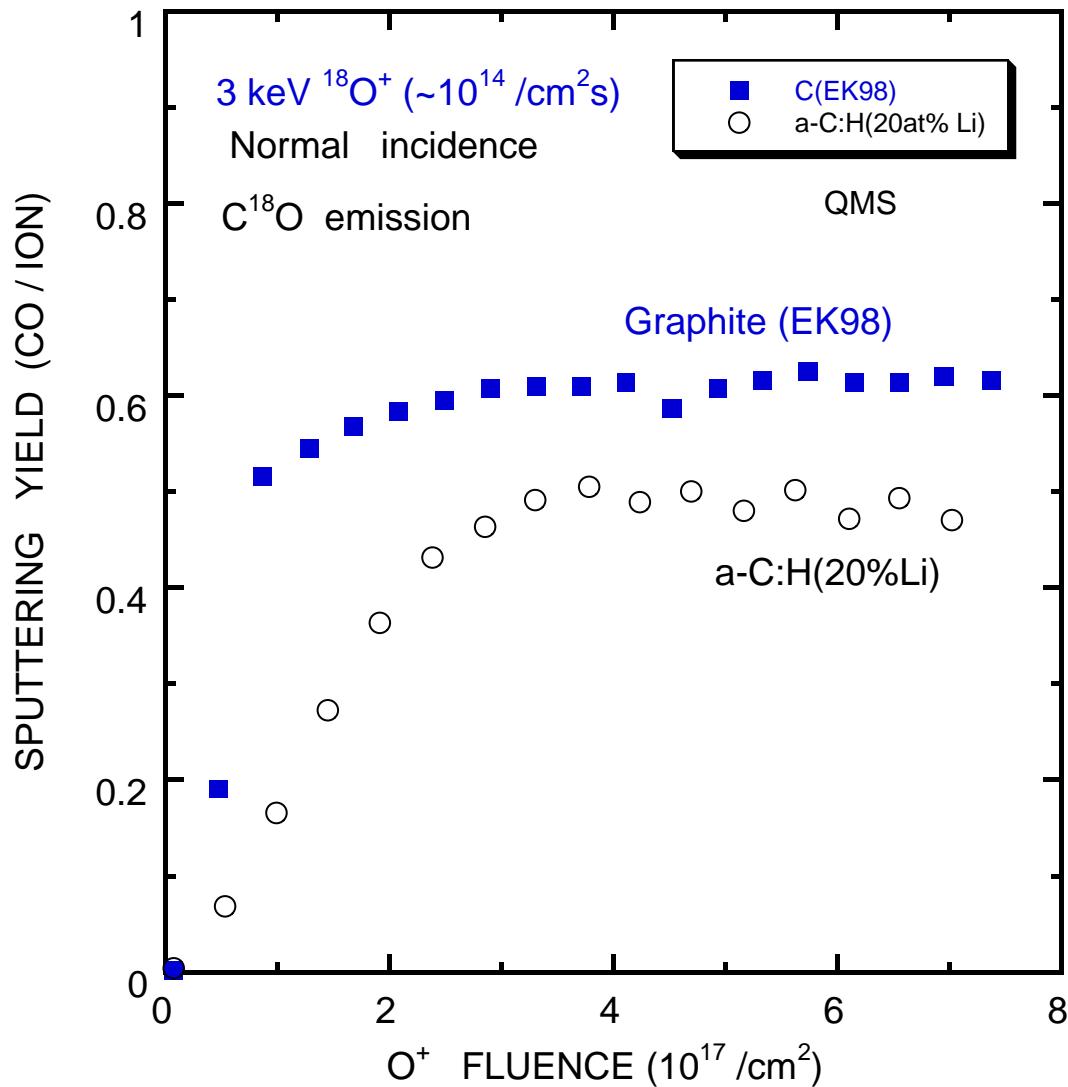
Fluence Dependence

Sp. Yield is very small for
 $<0.5 \times 10^{17} \text{ cm}^{-2}$,

Accumulation effect, ?

Li-doping: Little effect

TVO1997FF2



J.-U. Thiele, E. Vietzke, P. Oelhafen,
J. Nucl. Mater. 241-243(1997)1127.

Energy Distribution of CO at RT

Vietzke et al JNM220-222(1999)249.

Two component

Maxwell-Bolzman (MB) : $E \exp(-E/kT)$

&

Thompson (Collision-cascade sputtering) :

$E/(E+U)^3$, $U=0.25$ eV

Temperature Dependence (Compound)

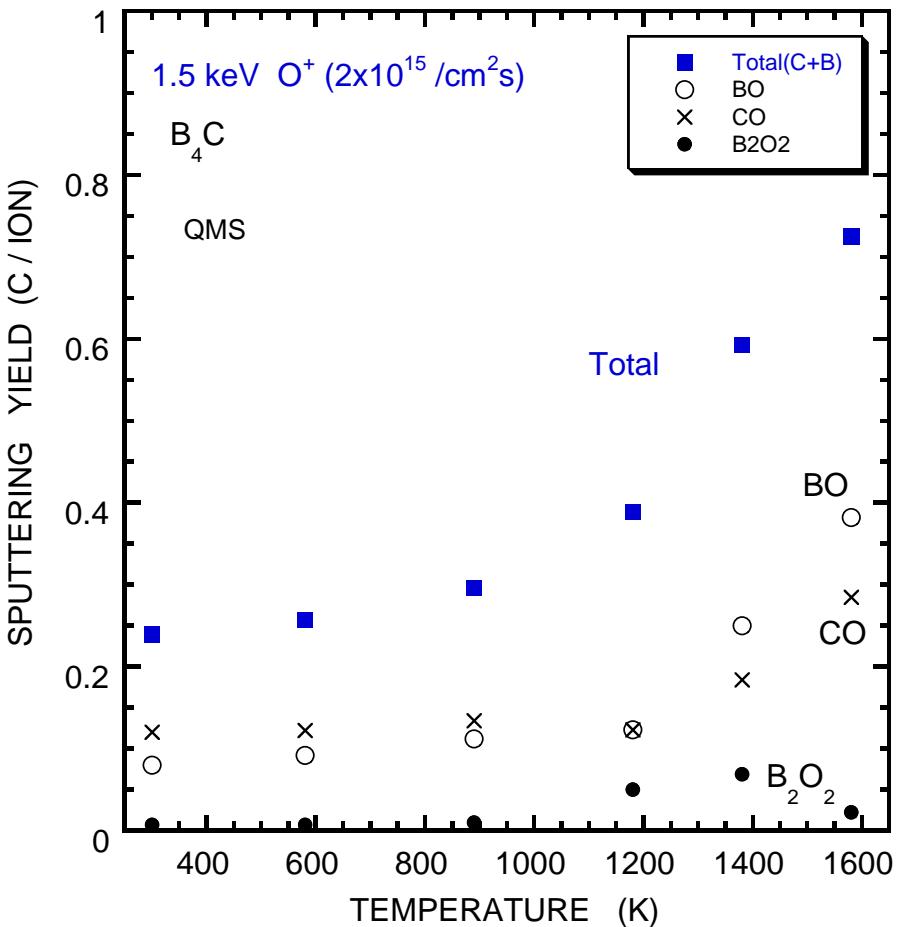
10

B₄C

Non-negligible chem. Sp.

CO, BO, B₂O₂

VRP1995TF5b

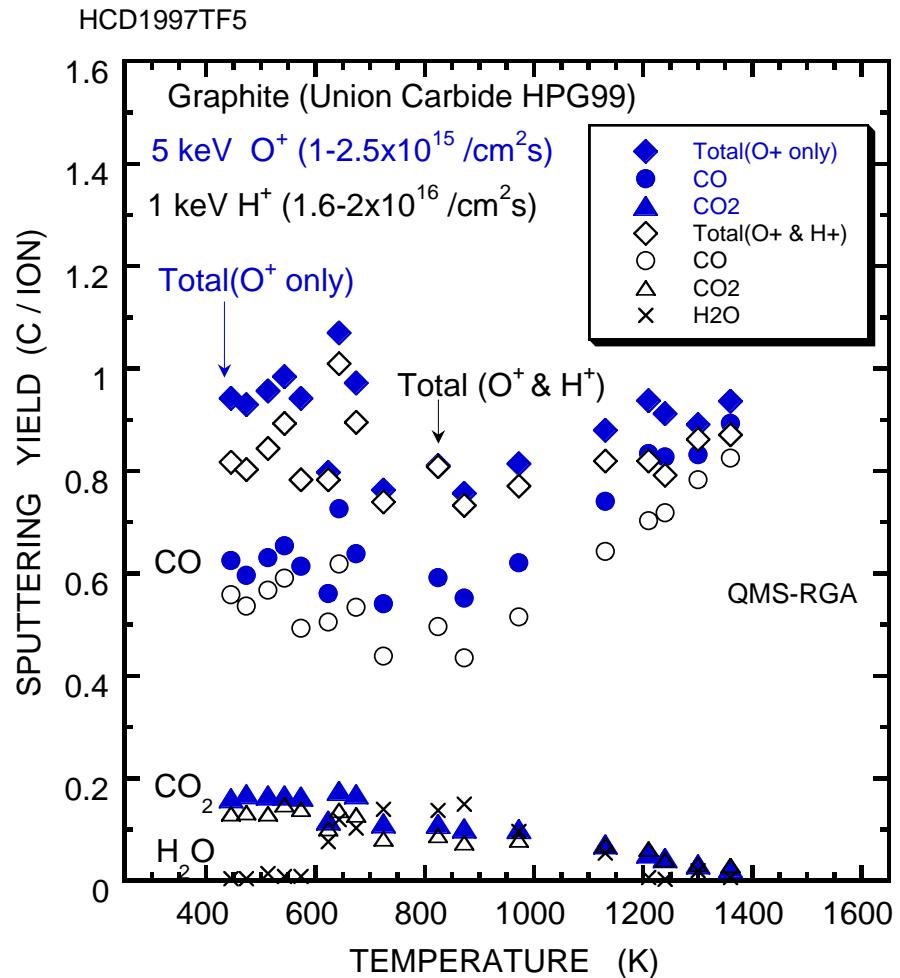


E. Vietzke, A. Refke, V. Philipps, M. Hennes,
J. Nucl. Mater. 220-222(1995)249.

Mix ion impact

5 keV O & 1 keV H

Little difference between
O and O & H impacts



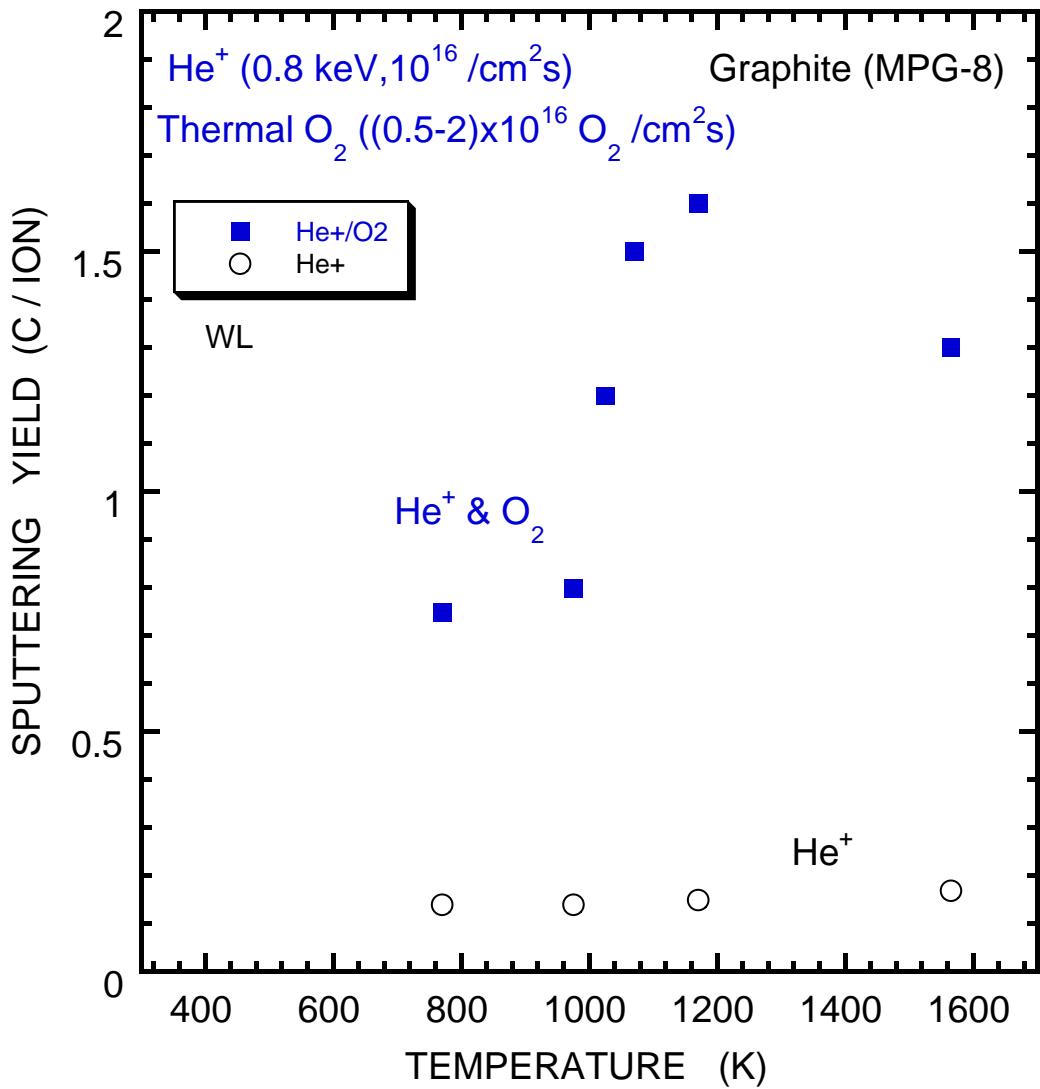
A. A. Haasz, A. Y. K. Chen, J. W. Davis, E. Vietzke,
J. Nucl. Mater. 248(1997)19.

Mix ion impact

Thermal O₂ & He⁺
impact:

Chem. Sp. appreciable

BBV1990TF2



L. B. Begrambekov, O. I. Buzhinsky, S. V. Vergasov, A. M. Zakharov,
V. G. Otroschenko, V. G. Telkovsky, J. Nucl. Mater. 176-177(1990)864.

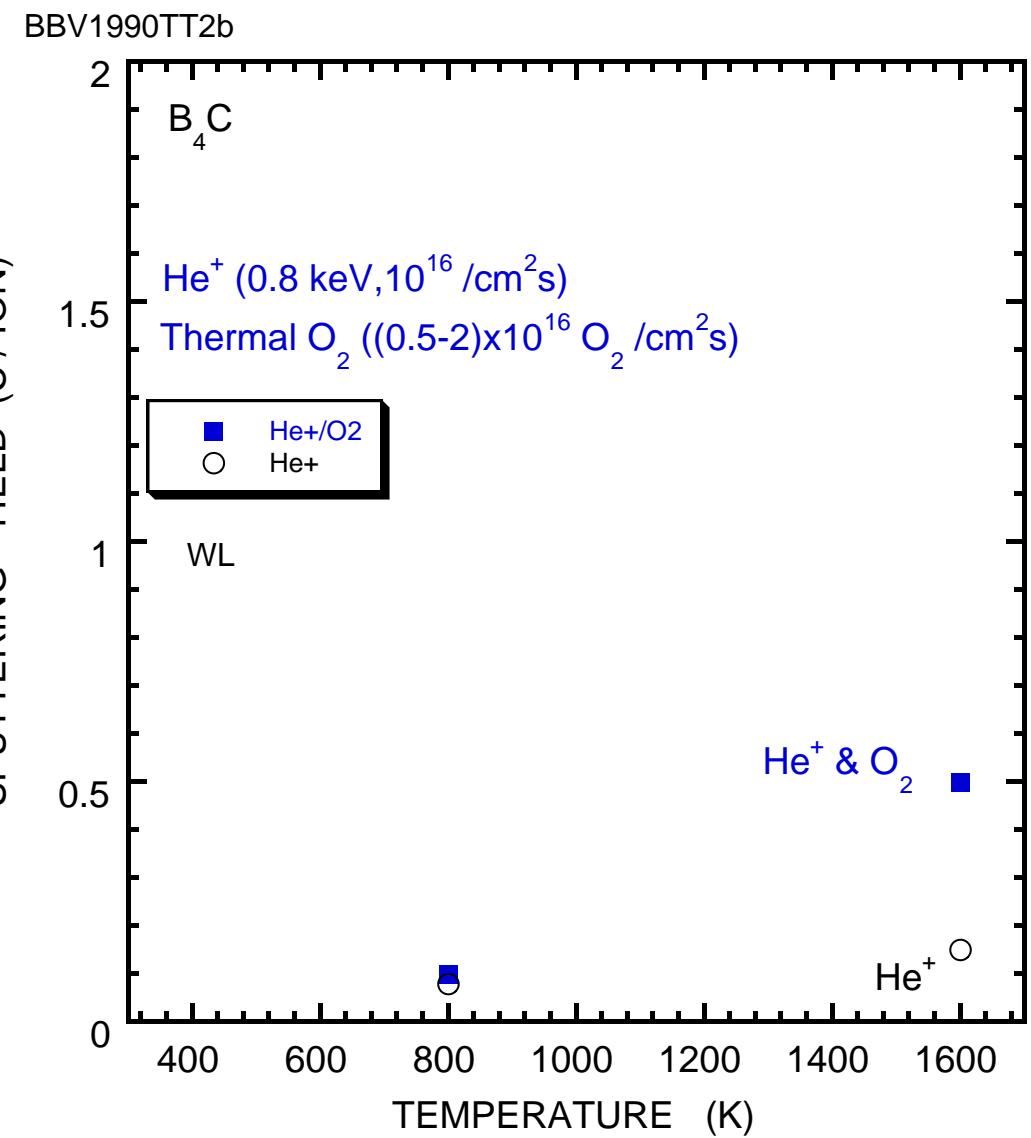
Mix ion impact

B₄C

No appreciable
chem. Sp.

B₄C+5at%TiC

Appreciable
chem. Sp.



Temperature dependence

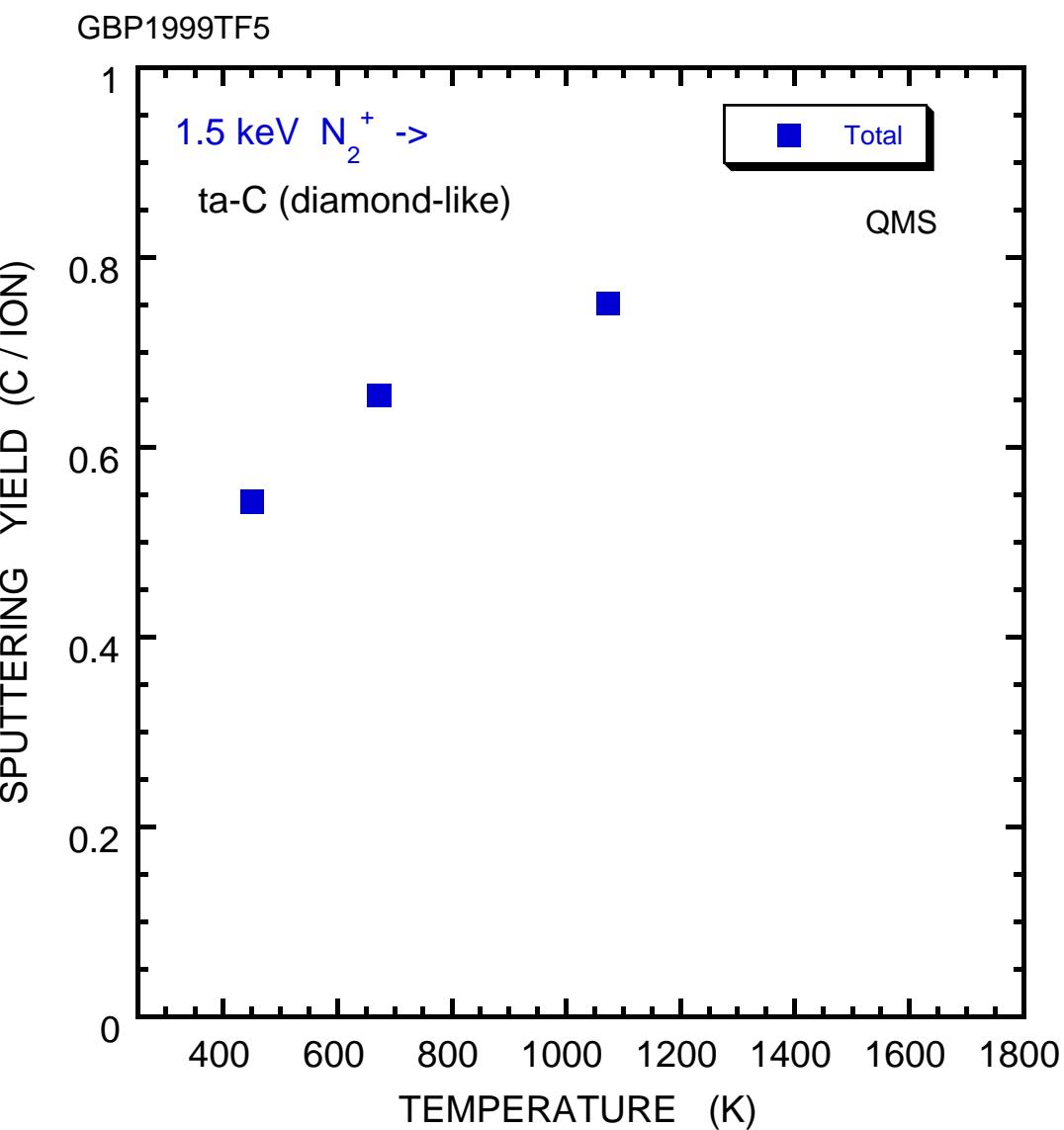
N ion impact

Chem. Sp. appreciable

Phys. Sp. = 0.29

(1984 version, Q=1.9)

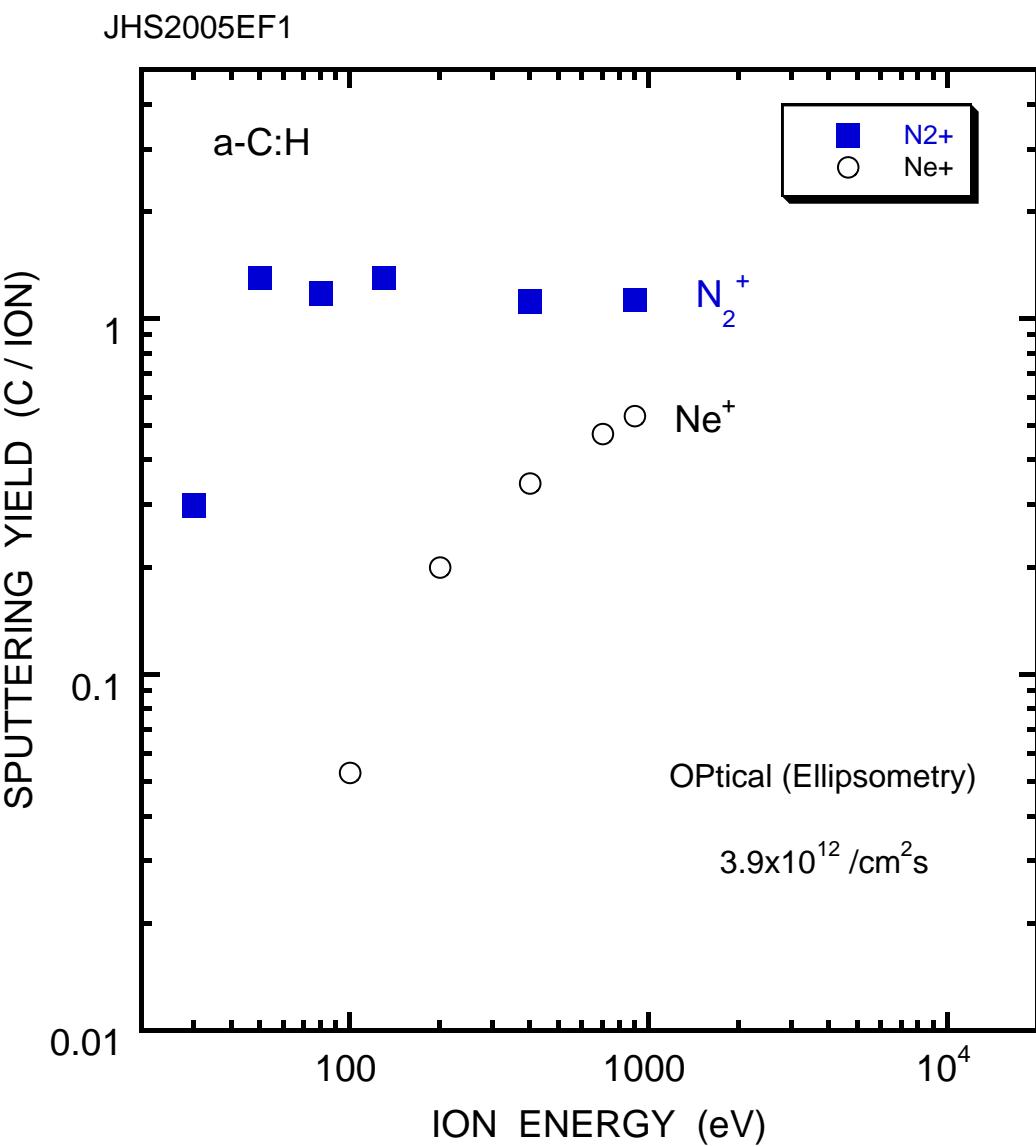
C_2N_2



Energy Dependence

N ion impact

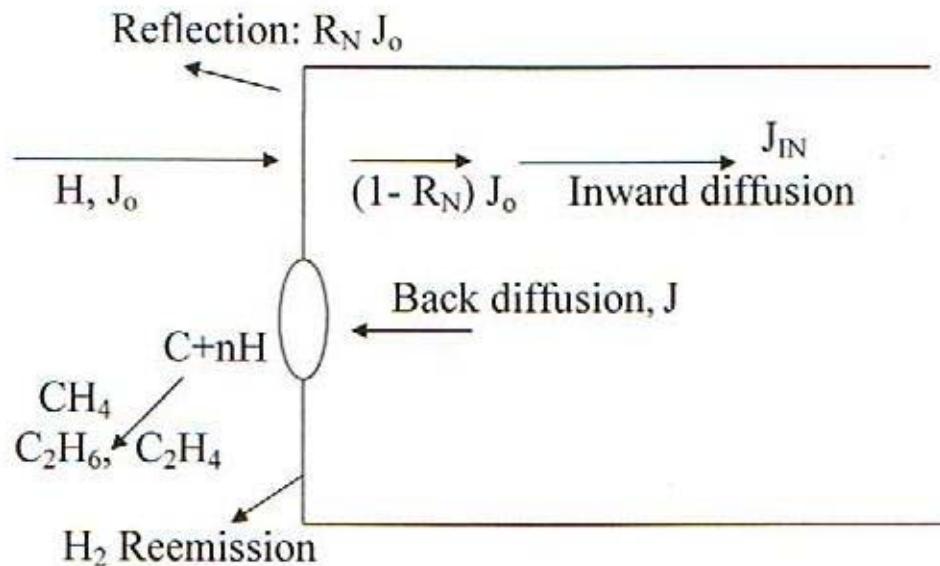
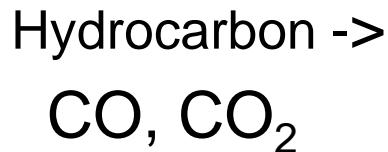
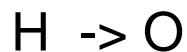
Chem. Sp.
appreciable



Model: pure graphite

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S.K.Erents, C.M.Braganza, G.M.McCracken, J. Nucl. Mat.63(1976)399.



$$Y_{\text{chem}} = n_H * \text{cnst} * \exp(-Q_1/RT),$$

$$n_H: H \text{ conc. at surfce, } \frac{dn_H}{dt} = J - J_o \sigma n_H - n_H / (\tau_o \exp(Q_2/RT))$$

ion-induced desorption thermal desorption

$Q_1: 159 \text{ kJ/mol, activation energy (heat of } CH_4 \text{ formation?)}$

$Q_2: 228 \text{ kJ/mol}$

$R_N: \text{Reflection coefficient}$

- Survey of chemical sputtering data: O, N impact effects
- Appreciable chemical sputtering
- CO is dominant for O impact
- Mechanism, similar to H impact??

Future problems

-
- A simple analytical formula?
- Reemission, Retention
- Isotope effect